



Material Content Data Sheet



Sales Product Name		BFR 193F H6327		Issued		25. January 2018			
MA#		MA001303746							
Package		PG-TSFP-3-1		Weight*		1.43 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	non noble metal	tin	7440-31-5	0.000	0.03		324		
	noble metal	gold	7440-57-5	0.002	0.13		1258		
	inorganic material	silicon	7440-21-3	0.016	1.09	1.25	10858	12440	
leadframe	inorganic material	silicon	7440-21-3	0.000	0.01		80		
	non noble metal	titanium	7440-32-6	0.001	0.04		400		
	non noble metal	chromium	7440-47-3	0.002	0.12		1199		
	non noble metal	copper	7440-50-8	0.570	39.78	39.95	397831	399510	
wire	noble metal	gold	7440-57-5	0.004	0.28	0.28	2810	2810	
	encapsulation	organic material	carbon black	1333-86-4	0.008	0.54		5445	
		plastics	epoxy resin	-	0.168	11.71		117071	
	inorganic material	silicondioxide	60676-86-0	0.605	42.19	54.44	422000	544516	
leadfinish	non noble metal	tin	7440-31-5	0.033	2.34	2.34	23351	23351	
plating	noble metal	silver	7440-22-4	0.025	1.74	1.74	17373	17373	
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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